## FOR UTILITY/DESIGN CIP/PCT NATIONAL/PLANT ORIGINAL/SUBSTITUTE/SUPPLEMENTAL DECLARATIONS

## RULE 63 (37 C.F.R. 1.63) DECLARATION AND POWER OF ATTO EY FOR PATENT APPLICATION IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PM&S FORM

50680-CS

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the INVENTION ENTITLED SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME the specification of which (CHECK applicable BOX(ES)) X -> [ X] is attached hereto. BOX(ES) as U.S. Application No. 0\_ and (if U.S. or PCT application amended) was amended on I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate filed by me or my assignee disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority claimed, before the filing date of this application: PRIOR FOREIGN APPLICATION(S) Date first Laid-Date Patented Priority Claimed Day/MONTH/Year Filed Number Country open or Published or Granted <u>Yes</u> <u>No</u> 10-182731 29/June/1998 Х Japan I hereby claim domestic priority benefit under 35 U.S.C. 119/120/365 of the indicated United States applications listed below and PCT international applications listed above or below and, if this is a continuation-in-part (CIP) application, insofar as the subject matter disclosed and claimed in this application is in addition to that disclosed in such prior applications, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56 which became available between the filing date of each such prior application and the national or PCT international filing date of this application: PRIOR U.S. PROVISIONAL. NONPROVISIONAL AND/OR PCT APPLICATION(S) Priority Claimed Day/MONTH/Year Filed Application No. (series code/serial no.) pending, abandoned, patented <u>Yes</u> No I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. And I hereby appoint Pillsbury Madison & Sutro LLP, Intellectual Property Group, 1100 New York Avenue, N.W., Ninth Floor. East Tower, Washington, D.C. 20005-3918, telephone number (202) 861-3000 (to whom all communications are to be directed), and the below-named persons (of the same address) individually and collectively my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent, and I hereby authorize them to delete names/numbers below of persons no longer with their firm and to act and rely on instructions from and communicate directly with the person/assignee/attorney/firm/ organization who/which first sends/sent this case to them and by whom/which I hereby declare that I have consented after full disclosure to be represented unless/until I instruct the above Firm and/or a below attorney in writing to the contrary. 27248 Paul N. Kokulis 18221 G. Paul Edgell 24238 Richard H. Zaitlen 16773 George M. Sirilla Raymond F. Lippitt Roger R. Wise 31204 17519 Donald J. Bird 25323 Lynn E. Eccleston 35861 G. Lloyd Knight 21082 17698 Peter W. Gowdey 25872 David A. Jakopin 32995 Jay M. Finkelstein Anita M. Kirkpatrick 32617 Carl G. Love 30793 18781 Dale S. Lazar 28872 Mark G. Paulson 36787 Michael R. Dzwonczyk Edgar H. Martin 20534 Glenn J. Perry 28458 Timothy J. Klima 34852 William K. West, Jr. 22057 30368 Stephen C. Glazier 31361 W. Patrick Bengtsson 32456 Kendrew H. Colton Kevin E. Joyce 20508 Paul E. White, Jr. 32011 Paul F. McQuade 31542 David\_W\_Brinkman Ruth N. Morduch 31044 20817 32331 Michelle N. Lester 1. INVENTOR'S SIGNATURE: Date trouis Japan Hiroyasu Ito Inventor's Name (typed) Country of Citizenship Middle Initial Family Name First Nagoya-city Jacen Residence (City) (State/Foreign Country) 448 Post Office Address (Include Zip Code) C/O DENSO CORPORATION, 1-1 Showa-cho, Kar 2. INVENTOR'S SIGNATURE: Date Japan Toshimasa Yamamoto Inventor's Name (typed)\_ Family Name Country of Citizenship Middle Initial First Ama-gun (State/Foreign Country) Residence (City) Aichi-prof. 448-8661 Japan Post Office Address (Include Zip Code) c/o DENSO CORPORATION, 1-1 Stown cho, Kariya city, Date 3. INVENTOR'S SIGNATURE: Inventor's Name (typed)\_ Country of Citizenship Family Name Middle Initial Residence (City) (State/Foreign Country) Post Office Address (Include Zip Code)

(FOR ADDITIONAL INVENTORS, check box [ ] and attach sheet (PAT-116.2) for same information for each re signature, name, date, citizenship, residence and address.)